

## Call for Papers

### Cross Society Special Issue (ISCAS & IFETC) on Flexible Hybrid Electronics: Advancing Next-Generation Applications

The scope of this Special Journal Issue includes materials and interface engineering, multi-physics simulation tools, system integration and packaging, interfacing circuits based on thin film transistors, optimization of hybrid system, and prototypes of flexible hybrid electronics (FHE). Authors are invited to submit papers on the process development, system simulations, signal/power/thermal integrity, flexible-rigid interfacing and energy harvesting aspects of potential FHE applications.

#### Topics (to be amended by Guest Editors)

- Applications based on flexible hybrid electronics
- Prototype and key components of FHE system
- Simulation methodologies for hybrid system
- Advanced Packing for hybrid system
- Flexible-rigid interface engineering
- Multi-physics modeling
- Stretchable/Shrinkable Sensors and Electronics
- Hybrid Systems-in-Foil
- Biomedical sensing devices
- Electronic textile/paper/skin
- Flexible/Printable Electronics in context with Circular Economy
- Organic/Inorganic/Hybrid Flexible Sensors and Electronics
- Emerging Materials for Flexible and Printable Systems
- Printable batteries, energy harvesters
- Wearable sensors
- Sensors for health monitoring
- Printable displays, lighting sources
- Smart tags, RFID tags, etc.
- Modeling of printable sensors
- Manufacturing Techniques (including Printing)
- 3D printing

#### Important dates (tentative)

<b>Immediately upon approval:</b>	Call for Papers (to appear in IEEE Journal on Flexible Electronics)
<b>08/2024:</b>	Deadline for Paper Submission
<b>09/2024:</b>	Completion of First Review
<b>10/2024:</b>	Completion of Final Review
<b>11/2024:</b>	Publication

#### Guest Editors (Generally about 4-8)

<b>Arokia Nathan,</b> University of Cambridge, United Kingdom Email - an299@cam.ac.uk	<b>Umit Y. Ogras,</b> University of Wisconsin-Madison, Wisconsin, USA Email - an299@cam.ac.uk	<b>Mengmeng Li,</b> Institute of Microelectronics of the Chinese Academy of Sciences, China Email - limengmeng@ime.ac.cn	<b>Ge Tong,</b> Nanyang Technological University, Singapore Email getong@ntu.edu.sg	<b>Leilai Shao,</b> Shanghai Jiao Tong University, China Email - leilaishao@sjtu.edu.cn
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#### Submission and Peer Review of Papers

All papers shall undergo the standard IEEE J-FLEX peer-review process. Manuscripts must be submitted online, via the *IEEE Manuscript Central*<sup>TM</sup>, see <https://mc.manuscriptcentral.com/jflex>. When submitting, please indicate in the "Manuscript Type" roll down menu, and also by e-mail to Mansi Kukreti, [m.kukreti@ieee.org](mailto:m.kukreti@ieee.org), that the paper is intended for the "<<insert Title of SI>>" Special Issue. Authors are particularly encouraged to **suggest names of potential reviewers** for their manuscripts in the space provided for these recommendations in *Manuscript Central*. For manuscript preparation and submission, please follow the guidelines in the *Information for Authors* at the IEEE J-FLEX web page, <https://ieee-jflex.org/guidelines-for-authors/>.